

## TPS3836E18-EP / J25-EP / H30-EP / L30-EP / K33-EP TPS3837E18-EP / J25-EP / L30-EP / K33-EP TPS3838E18-EP / J25-EP / L30-EP / K33-EP

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SGLS322D-MAY 2006-REVISED NOVEMBER 2008

## NANOPOWER SUPERVISORY CIRCUITS

#### **FEATURES**

- ESD Protection Exceeds 2000 V Per MIL-STD-883, Method 3015; Exceeds 200 V Using Machine Model (C = 200 pF, R = 0)
- Supply Current of 220 nA (Typ)
- Precision Supply Voltage Supervision Range:
   1.8 V, 2.5 V, 3 V, 3.3 V
- Power-On Reset Generator With Selectable Delay Time of 10 ms or 200 ms
- Push/Pull RESET Output (TPS3836), RESET Output (TPS3837), or Open-Drain RESET Output (TPS3838)
- Manual Reset
- 5-Pin SOT-23 Package

## SUPPORTS DEFENSE, AEROSPACE, AND MEDICAL APPLICATIONS

- Controlled Baseline
- One Assembly/Test Site
- One Fabrication Site
- Available in Military (–55°C/125°C)
   Temperature Range<sup>(1)</sup>
- Extended Product Life Cycle
- Extended Product-Change Notification
- Product Traceability

## **APPLICATIONS**

- Applications Using Automotive Low-Power DSPs, Microcontrollers, or Microprocessors
- Battery-Powered Equipment
- Intelligent Instruments
- Wireless Communication Systems
- Automotive Systems
- (1) Custom temperature ranges available

#### **DESCRIPTION**

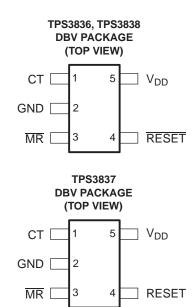
The TPS3836, TPS3837, TPS3838 families of supervisory circuits provide circuit initialization and timing supervision, primarily for digital signal processing (DSP) and processor-based systems.

During power on,  $\overline{\text{RESET}}$  is asserted when the supply voltage  $V_{DD}$  becomes higher than 1.1 V. Thereafter, the supervisory circuit monitors  $V_{DD}$  and keeps  $\overline{\text{RESET}}$  output active as long as  $V_{DD}$  remains below the threshold voltage  $(V_{IT})$ . An internal timer delays the return of the output to the inactive state (high) to ensure proper system reset. The delay time starts after  $V_{DD}$  has risen above  $V_{IT}$ .

When CT is connected to GND, a fixed delay time of typical 10 ms is asserted. When connected to  $V_{DD}$ , the delay time is typically 200 ms.



Please be aware that an important notice concerning availability, standard warranty, and use in critical applications of Texas Instruments semiconductor products and disclaimers thereto appears at the end of this data sheet.



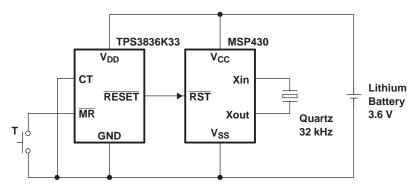


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When the supply voltage drops below  $V_{IT}$ , the output becomes active (low) again.

All the devices of this family have a fixed-sense V<sub>IT</sub> set by an internal voltage divider.

The TPS3836 has an active-low push-pull RESET output. The TPS3837 has active-high push-pull RESET, and the TPS3838 integrates an active-low open-drain RESET output.



**Figure 1. Typical Operating Circuit** 

The product spectrum is designed for supply voltages of 1.8 V, 2.5 V, 3 V, and 3.3 V. The circuits are available in a 5-pin SOT-23 package. The TPS3836, TPS3837, and TPS3838 families are characterized for operation over a temperature range of –55°C to 125°C.

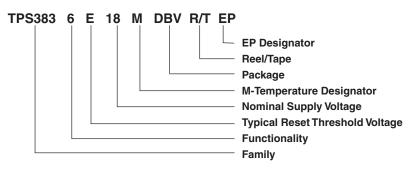


#### **ORDERING INFORMATION**

T <sub>A</sub>	ORDERABLE PART NUMBER <sup>(1)</sup>	THRESHOLD VOLTAGE	SYMBOL	
	TPS3836J25MDBVTEP	2.25 V	PKRM	
-55°C to 125°C	TPS3836L30MDBVREP	2.64 V	BTX	
	TPS3837K33MDBVREP	2.93 V	PKZM	

(1) DBVR indicates reel of 3000 parts, DBVT indicates tape of 250 parts.

## **ORDERING INFORMATION**



#### **FUNCTION TABLE**

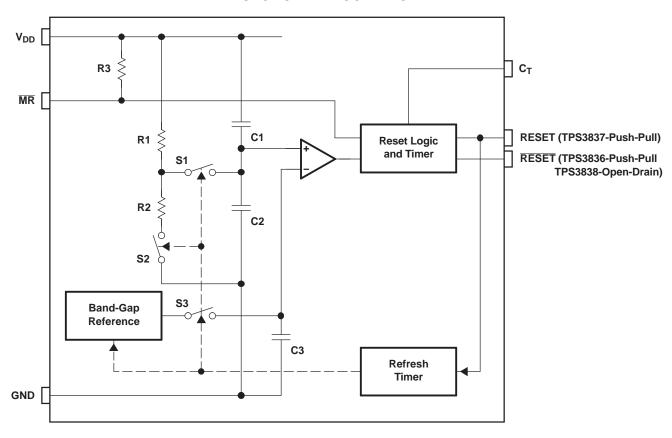
MR	$V_{DD} > V_{IT}$	RESET (1)	RESET <sup>(2)</sup>
L	0	L	Н
L	1	L	Н
Н	0	L	Н
Н	1	Н	L

- (1) TPS3836 and TPS3838
- (2) TPS3837

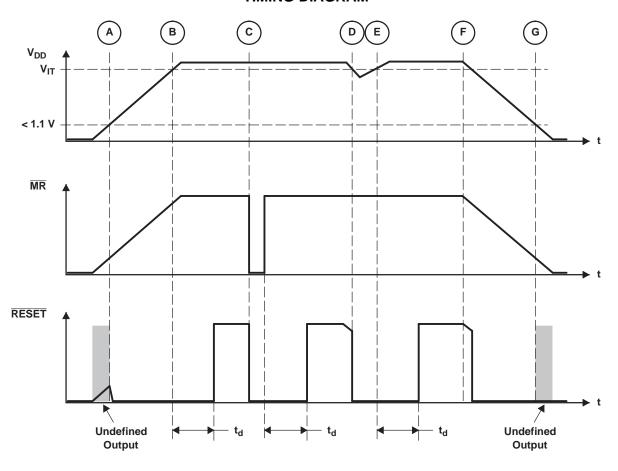


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#### **FUNCTIONAL BLOCK DIAGRAM**



#### **TIMING DIAGRAM**



## **Absolute Maximum Ratings**

over operating free-air temperature range (unless otherwise noted) (1)

$V_{DD}$	Supply voltage (2)	7 V
	All other pins <sup>(2)</sup>	–0.3 V to 7 V
I <sub>OL</sub>	Maximum low output current	5 mA
I <sub>OH</sub>	Maximum high output current	–5 mA
I <sub>IK</sub>	Input clamp current $(V_I < 0 \text{ or } V_I > V_{DD})$	±10 mA
I <sub>OK</sub>	Output clamp current ( $V_O < 0$ or $V_O > V_{DD}$ )	±10 mA
T <sub>A</sub>	Operating free-air temperature range	–55°C to 125°C
T <sub>stg</sub>	Storage temperature range	-65°C to 150°C
$T_{J}$	Maximum junction temperature	150°C
	Soldering temperature	260°C

<sup>(1)</sup> Stresses beyond those listed under absolute maximum ratings may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under recommended operating conditions is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

<sup>(2)</sup> All voltage values are with respect to GND. For reliable operation, the device must not be continuously operated at 7 V for more than t = 1000 h.



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#### **Thermal Resistance Table**

RESISTANCE	HIGH	LOW
θ <sub>JC</sub> (°C/W)	130.9	148.1
θ <sub>JA</sub> (°C/W)	205.6	347

## **Recommended Operating Conditions**

		MIN	MAX	UNIT
$V_{DD}$	Supply voltage	1.6	6	V
$V_{I}$	Input voltage	0	$V_{DD} + 0.3$	V
$V_{IH}$	High-level input voltage	$0.7 \times V_{DD}$		V
V <sub>IL</sub>	Low-level input voltage		$0.3 \times V_{DD}$	V
Δt/Δν	Input transition rise and fall rate at MR		100	ns/V
T <sub>A</sub>	Operating free-air temperature	-55	125	°C

#### **Electrical Characteristics**

over recommended operating conditions (unless otherwise noted)

	PARAMET	ER	TEST CONDI	TEST CONDITIONS		TYP	MAX	UNIT
	$\overline{\text{RESET}}$ $V_{DD} = 3.3 \text{ V}, I_{OH} = -2 \text{ mA}$							
.,	High-level output	(TPS3836)	$V_{DD} = 6 \text{ V}, I_{OH} = -3 \text{ mA}$	$V_{DD} = 6 \text{ V}, I_{OH} = -3 \text{ mA}$				V
$V_{OH}$	voltage	RESET	$V_{DD} = 2 \text{ V}, I_{OH} = -1 \text{ mA}$		$0.8 \times V_{DD}$			V
		(TPS3837)	$V_{DD} = 3.3 \text{ V}, I_{OH} = -2 \text{ mA}$					
		RESET	$V_{DD} = 2 \text{ V}, I_{OL} = 1 \text{ mA}$					
.,	Low-level output	(TPS3836/8)	$V_{DD} = 3.3 \text{ V}, I_{OL} = 2 \text{ mA}$				0.4	V
$V_{OL}$	voltage	RESET	$V_{DD} = 3.3 \text{ V}, I_{OL} = 2 \text{ mA}$				0.4	V
		(TPS3837)	$V_{DD} = 6 \text{ V}, I_{OL} = 3 \text{ mA}$					
		TPS3836/8	$V_{DD} \ge 1.1 \text{ V}, I_{OL} = 50 \mu\text{A}$				0.2	
	Power-up reset voltage <sup>(1)</sup>	TDC2027	V >1.1 V I 50 A	T <sub>A</sub> = 25°C	0.8 × V <sub>DD</sub>			V
	vollago	TPS3837	$V_{DD} \ge 1.1 \text{ V}, I_{OH} = -50 \mu\text{A}$	T <sub>A</sub> = Full range	0.6 × V <sub>DD</sub>			
		TPS383xE18			1.64	1.71	1.73	
		TPS383xJ25		2.16	2.25	2.31		
\/	Negative-going	TPS383xH30			2.7	2.79	2.85	V
V <sub>IT</sub>	input threshold voltage <sup>(2)</sup>	TPS383xL30			2.54	2.64	2.71	V
	· ·	TPS383xK33	T <sub>A</sub> = 25°C		2.82	2.93	3.1	
		1P3363XN33	T <sub>A</sub> = Full range	2.72	2.93	3.2		
			1.7 V < V <sub>IT</sub> < 2.5 V	1.7 V < V <sub>IT</sub> < 2.5 V		30		
$V_{\text{hys}}$	Hysteresis at V <sub>DD</sub> in	nput	2.5 V < V <sub>IT</sub> < 3.5 V			40		mV
			$3.5 \text{ V} < \text{V}_{\text{IT}} < 5 \text{ V}$			50		
		MR (3)	$\overline{MR} = 0.7 \times V_{DD}, V_{DD} = 6 \text{ V}$	T <sub>A</sub> = 25°C	-30	-60	-90	^
I <sub>IH</sub>	High-level input display the current display t		$VIR = 0.7 \times V_{DD}, V_{DD} = 6 V$	T <sub>A</sub> = Full range	-20	-60	-120	μΑ
	carrent	СТ	CT = V <sub>DD</sub> = 6 V		-25		25	nA
		MR (3)	$\overline{MR} = 0 \text{ V}, \text{ V}_{DD} = 6 \text{ V}$	T <sub>A</sub> = 25°C	-130	-200	-340	
$I_{\text{IL}}$	Low-level input current	IVITY \'	$ v  = 0 \ v, \ v_{DD} = 0 \ v$	T <sub>A</sub> = Full range	-90	-200	-350	μΑ
		СТ	CT = 0 V, V <sub>DD</sub> = 6 V		-25		25	nA
I <sub>OH</sub>	High-level output current	TPS3838	$V_{DD} = V_{IT} + 0.2 \text{ V}, V_{OH} = V_{DD}$	$V_{DD} = V_{IT} + 0.2 \text{ V}, V_{OH} = V_{DD}$			25	nA

<sup>(1)</sup> The lowest voltage at which  $\overline{RESET}$  output becomes active,  $t_r$ ,  $V_{DD} \ge 15 \mu s/V$ 

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<sup>(2)</sup> To ensure best stability of the threshold voltage, a bypass capacitor (ceramic, 0.1 µF) should be placed near the supply terminal.

<sup>(3)</sup> If manual reset is unused, MR should be connected to V<sub>DD</sub> to minimize current consumption.



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## **Electrical Characteristics (continued)**

over recommended operating conditions (unless otherwise noted)

	PARAMETER	TEST CON	IDITIONS	MIN	TYP	MAX	UNIT
		V - V - V 2 V	T <sub>A</sub> = 25°C		220	500	
		$V_{DD} > V_{IT}, V_{DD} < 3 V$	T <sub>A</sub> = Full range			600	- 4
	Cumply augrent	V - V - V - 2 V	T <sub>A</sub> = 25°C		250	550	nA
IDD	I <sub>DD</sub> Supply current	$V_{DD} > V_{IT}, V_{DD} > 3 V$	T <sub>A</sub> = Full range			650	
		V · ·V	T <sub>A</sub> = 25°C		10	25	^
		$V_{DD} < V_{IT}$	T <sub>A</sub> = Full range			30	μΑ
	Internal pullup resistor at MR				33		kΩ
Cı	Input capacitance at MR, CT	$V_I = 0 \text{ V to } V_{DD}$			5		pF

## **Timing Requirements**

 $R_L = 1 \text{ M}\Omega, C_L = 50 \text{ pF}, T_A = 25^{\circ}\text{C}$ 

PARAMETER		ETER	TEST CONDITIONS		UNIT
	Dula a videla	At V <sub>DD</sub>	$V_{IH} = V_{IT} + 0.2 \text{ V}, V_{IL} = V_{IT} - 0.2 \text{ V}$	6	μs
ι <sub>w</sub>	Pulse width	At MR	$V_{DD} \ge V_{IT} + 0.2 \text{ V}, V_{IL} = 0.3 \times V_{DD}, V_{IH} = 0.7 \times V_{DD}$	1	μs

## **Switching Characteristics**

 $R_L = 1 \text{ M}\Omega$ ,  $C_L = 50 \text{ pF}$ ,  $T_A = 25^{\circ}\text{C}$ 

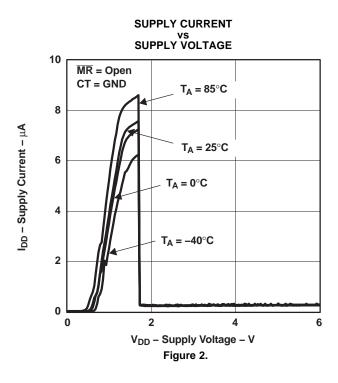
PARAMETER		TEST CONDITIONS	MIN	TYP	MAX	UNIT		
	Delay time		$V_{DD} \ge V_{IT} + 0.2 \text{ V}, \overline{MR} = 0.7 \times V_{DD},$	CT = GND	5	10	15	mo
t <sub>d</sub>	Delay liffle		See timing diagram	$CT = V_{DD}$		200		ms
	Propagation (delay)	V <sub>DD</sub> to RESET delay	$V_{IL} = V_{IT} - 0.2 \text{ V}, V_{IH} = V_{IT} + 0.2 \text{ V}$			10		
t <sub>PHL</sub>	time, high- to low-level output	(TPS3836, TPS3838)	11 4011			50		μs
	Propagation (delay)	V <sub>DD</sub> to RESET delay	$V_{IL} = V_{IT} - 0.2 \text{ V}, V_{IH} = V_{IT} + 0.2 \text{ V}$		10			
t <sub>PLH</sub>	time, low- to high-level output	(TPS3837)	V <sub>IL</sub> = 1.6 V			50		μs
t <sub>PHL</sub>	Propagation (delay) time, high- to low-level output	MR to RESET delay (TPS3836, TPS3838)	$V_{DD} \ge V_{IT} + 0.2 \text{ V}, V_{IL} = 0.3 \times V_{DD}, V_{IH} = 0.7 \times V_{DD}$			0.3		μs
t <sub>PLH</sub>	Propagation (delay) time, low- to high-level output	MR to RESET delay (TPS3837)	$V_{DD} \ge V_{IT} + 0.2 \text{ V}, V_{IL} = 0.3 \times V_{DD}, V_{IH} = 0.7 \times V_{DD}$ 0.3				μs	

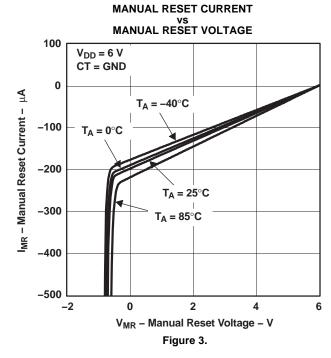


#### TYPICAL CHARACTERISTICS

## **Table of Graphs**

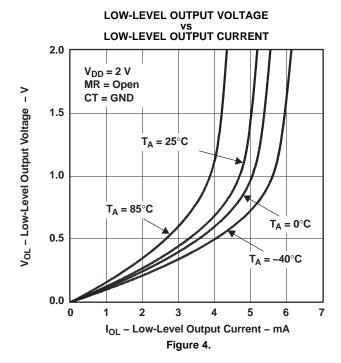
			FIGURE
$I_{DD}$	Supply current	vs Supply voltage	2
I <sub>MR</sub>	Manual reset current	vs Manual reset voltage	3
$V_{OL}$	Low-level output voltage	vs Low-level output current	4
$V_{OH}$	High-level output voltage	vs High-level output current	5
	Normalized reset threshold voltage	vs Free-air temperature	6
	Minimum pulse duration at V <sub>DD</sub>	vs V <sub>DD</sub> threshold overdrive	7



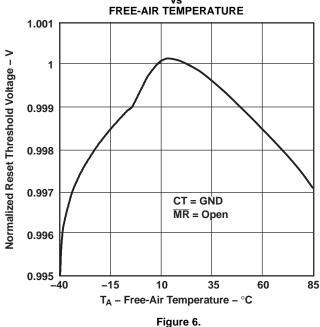




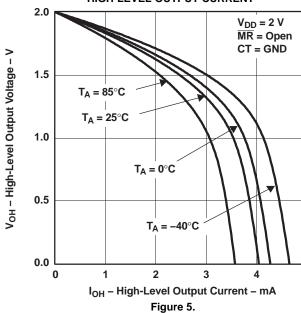




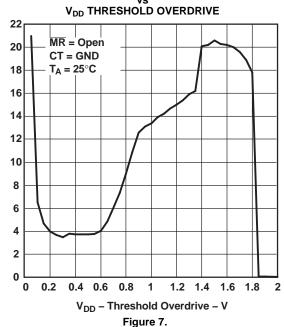
## NORMALIZED RESET THRESHOLD VOLTAGE



# HIGH-LEVEL OUTPUT VOLTAGE vs HIGH-LEVEL OUTPUT CURRENT



## MINIMUM PULSE DURATION AT V<sub>DD</sub>



Minimum Pulse Duration at  $V_{DD} - \mu s$ 

5

#### PACKAGE OPTION ADDENDUM



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#### **PACKAGING INFORMATION**

Orderable Device	Status <sup>(1)</sup>	Package Type	Package Drawing	Pins	Package Qty	e Eco Plan <sup>(2)</sup>	Lead/Ball Finish	MSL Peak Temp <sup>(3)</sup>
2T36L30MDBVREPG4	ACTIVE	SOT-23	DBV	5	3000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
TPS3836J25MDBVTEP	ACTIVE	SOT-23	DBV	5	250	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
TPS3836L30MDBVREP	ACTIVE	SOT-23	DBV	5	3000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
TPS3837K33MDBVREP	ACTIVE	SOT-23	DBV	5	3000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
TPS3837K33QDBVREP	ACTIVE	SOT-23	DBV	5	3000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
V62/06637-09XE	ACTIVE	SOT-23	DBV	5	3000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
V62/06637-15XE	ACTIVE	SOT-23	DBV	5	250	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
V62/06637-17XE	ACTIVE	SOT-23	DBV	5	3000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
V62/06637-22XE	ACTIVE	SOT-23	DBV	5	3000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM

(1) The marketing status values are defined as follows:

ACTIVE: Product device recommended for new designs.

LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

**NRND:** Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

**PREVIEW:** Device has been announced but is not in production. Samples may or may not be available.

**OBSOLETE:** TI has discontinued the production of the device.

(2) Eco Plan - The planned eco-friendly classification: Pb-Free (RoHS), Pb-Free (RoHS Exempt), or Green (RoHS & no Sb/Br) - please check http://www.ti.com/productcontent for the latest availability information and additional product content details.

TBD: The Pb-Free/Green conversion plan has not been defined.

**Pb-Free** (RoHS): Ti's terms "Lead-Free" or "Pb-Free" mean semiconductor products that are compatible with the current RoHS requirements for all 6 substances, including the requirement that lead not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, TI Pb-Free products are suitable for use in specified lead-free processes.

**Pb-Free (RoHS Exempt):** This component has a RoHS exemption for either 1) lead-based flip-chip solder bumps used between the die and package, or 2) lead-based die adhesive used between the die and leadframe. The component is otherwise considered Pb-Free (RoHS compatible) as defined above.

Green (RoHS & no Sb/Br): TI defines "Green" to mean Pb-Free (RoHS compatible), and free of Bromine (Br) and Antimony (Sb) based flame retardants (Br or Sb do not exceed 0.1% by weight in homogeneous material)

(3) MSL, Peak Temp. -- The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

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#### OTHER QUALIFIED VERSIONS OF TPS3836J25-EP, TPS3836L30-EP, TPS3837K33-EP:

Catalog: TPS3836J25, TPS3836L30, TPS3837K33

## **PACKAGE OPTION ADDENDUM**



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• Automotive: TPS3836J25-Q1, TPS3836L30-Q1, TPS3837K33-Q1

NOTE: Qualified Version Definitions:

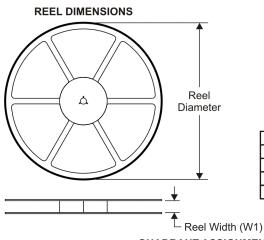
- Catalog TI's standard catalog product
- Automotive Q100 devices qualified for high-reliability automotive applications targeting zero defects

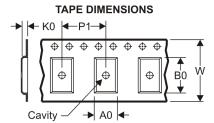




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## TAPE AND REEL INFORMATION





Α	0	Dimension designed to accommodate the component width
В	0	Dimension designed to accommodate the component length
		Dimension designed to accommodate the component thickness
٧	٧	Overall width of the carrier tape
ГР	1	Pitch between successive cavity centers

## QUADRANT ASSIGNMENTS FOR PIN 1 ORIENTATION IN TAPE

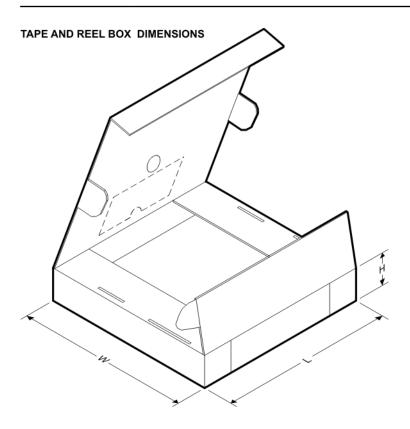


\*All dimensions are nominal

Device	Package Type	Package Drawing		SPQ	Reel Diameter (mm)	Reel Width W1 (mm)	A0 (mm)	B0 (mm)	K0 (mm)	P1 (mm)	W (mm)	Pin1 Quadrant
TPS3836J25MDBVTEP	SOT-23	DBV	5	250	180.0	9.0	3.15	3.2	1.4	4.0	8.0	Q3
TPS3836L30MDBVREP	SOT-23	DBV	5	3000	180.0	9.0	3.15	3.2	1.4	4.0	8.0	Q3
TPS3837K33MDBVREP	SOT-23	DBV	5	3000	180.0	9.0	3.15	3.2	1.4	4.0	8.0	Q3
TPS3837K33QDBVREP	SOT-23	DBV	5	3000	180.0	9.0	3.15	3.2	1.4	4.0	8.0	Q3

## PACKAGE MATERIALS INFORMATION

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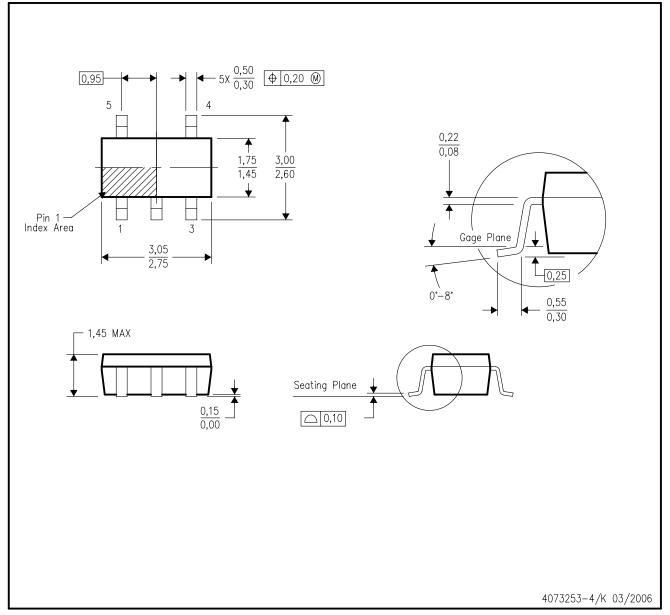


#### \*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Length (mm)	Width (mm)	Height (mm)
TPS3836J25MDBVTEP	SOT-23	DBV	5	250	182.0	182.0	20.0
TPS3836L30MDBVREP	SOT-23	DBV	5	3000	182.0	182.0	20.0
TPS3837K33MDBVREP	SOT-23	DBV	5	3000	182.0	182.0	20.0
TPS3837K33QDBVREP	SOT-23	DBV	5	3000	182.0	182.0	20.0

## DBV (R-PDSO-G5)

## PLASTIC SMALL-OUTLINE PACKAGE



NOTES:

- A. All linear dimensions are in millimeters.
- B. This drawing is subject to change without notice.
- C. Body dimensions do not include mold flash or protrusion. Mold flash and protrusion shall not exceed 0.15 per side.
- D. Falls within JEDEC MO-178 Variation AA.

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